

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions and listings of claims in the application:

**Listing of Claims:**

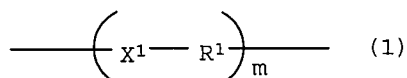
Please amend the claims as follows:

1. (Withdrawn) A resin composition used as an adhesive bonding a semiconductor chip or a heat dissipating member comprising a filler (A), the following compound (B) and a thermal radical initiator (C), and substantially not containing a photo polymerization initiator:

Compound (B):

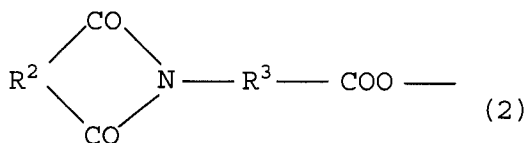
a compound containing a structure represented by the following formula (1) in a main chain and having at least one functional group represented by the following formula (2):

Formula (1):



wherein X<sup>1</sup> is -O-, -COO- or -OCOO-; R<sup>1</sup> is a hydrocarbon group having 1 to 6 carbons; "m" is an integer from 1 to 50; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other;

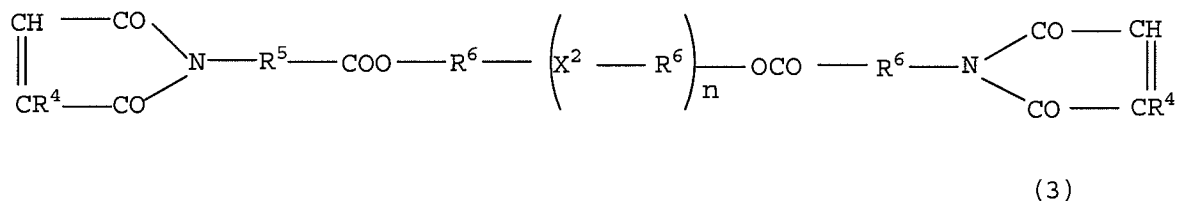
Formula (2):



wherein R<sup>2</sup> is -CH=CH- or -CH=CH-CH<sub>2</sub>-; R<sup>3</sup> is a hydrocarbon group having 1 to 11 carbons; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.

2. (Withdrawn) A resin composition according to Claim 1, wherein the filler (A) is silver powder.
3. (Withdrawn) A resin composition according to Claim 1, wherein  $X^1$  of the compound (B) is  $-O-$ .
4. (Withdrawn) A resin composition according to Claim 1, wherein  $R^1$  of the compound (B) is a hydrocarbon group having 3 to 6 carbons.
5. (Withdrawn) A resin composition according to Claim 4, wherein  $R^1$  of the compound (B) is at least one selected from the group consisting of  $-C_3H_6-$  and  $-C_4H_8-$ .
6. (Withdrawn) A resin composition according to Claim 1, wherein  $R^2$  is  $-C_2H_2-$  and  $R^3$  is  $-CH_2-$  in the compound (B).
7. (Withdrawn) A resin composition according to Claim 1, wherein the compound (B) has two functional groups represented by the formula (2).
8. (Withdrawn) A resin composition according to Claim 1, wherein the compound (B) is a bis-maleimide compound (B') represented by the following formula (3):

Formula (3):



wherein  $X^2$  is  $-O-$ ,  $-COO-$  or  $-OCOO-$ ; each  $R^4$  is hydrogen atom or a methyl group; each  $R^5$  is a hydrocarbon group having 1 to 11 carbons; each  $R^6$  is a hydrocarbon group having 3 to 6 carbons; "n" is an integer from 1 to 50; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.

9. (Withdrawn) A resin composition according to Claim 8, wherein  $X^2$  of the

bis-maleimide compound (B') represented by the formula (3) is -O-.

10. (Withdrawn) A resin composition according to Claim 8, wherein R<sup>5</sup> of the bis-maleimide compound (B') represented by the formula (3) is a hydrocarbon group not containing an aromatic group.

11. (Withdrawn) A resin composition according to Claim 8, wherein R<sup>5</sup> of the bis-maleimide compound (B') represented by the formula (3) has 1 to 5 carbons.

12. (Withdrawn) A resin composition according to Claim 8, wherein R<sup>5</sup> of the bis-maleimide compound (B') represented by the formula (3) is -CH<sub>2</sub>- or -C<sub>5</sub>H<sub>10</sub>-.

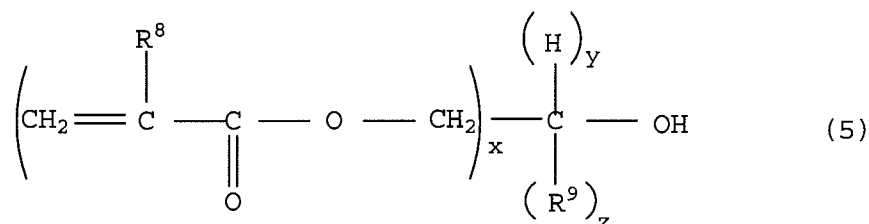
13. (Withdrawn) A resin composition according to Claim 8, wherein R<sup>6</sup> of the bis-maleimide compound (B') represented by the formula (3) is at least one selected from the group consisting of -C<sub>3</sub>H<sub>6</sub>- and -C<sub>4</sub>H<sub>8</sub>-.

14. (Cancelled)

15. (Withdrawn) A resin composition according to Claim 1, further containing the following acrylic ester compound (E):

Acrylic ester compound (E):

Formula (5):



wherein R<sup>8</sup> is hydrogen atom or a methyl group; R<sup>9</sup> is a hydrocarbon group having 1 to 3 carbons; "x", "y" and "z" are in the relationship expressed by (x+y+z)=3, 1≤x≤3, 0≤y≤2 and 0≤z≤2; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.

16. (Withdrawn) A resin composition according to Claim 1, wherein  $R^8$  of the acrylic ester compound (E) represented by the formula (5) is a methyl group.
17. (Withdrawn) A resin composition according to Claim 1, wherein  $R^9$  of the acrylic ester compound (E) represented by the formula (5) is a methyl group.
18. (Withdrawn) A resin composition according to Claim 1, wherein  $R^8$  is a methyl group,  $R^9$  is a methyl group, and  $x=1$ ,  $y=1$ , and  $z=1$  in the acrylic ester compound (E) represented by the formula (5).
19. (Withdrawn) A resin composition according to Claim 1, wherein  $R^8$  is a methyl group,  $x=2$ ,  $y=1$  and  $z=0$  in the acrylic ester compound (E) represented by the formula (5).
20. (Withdrawn) A resin composition according to Claim 1, further comprising the following acrylamide compound (F):  
Acrylamide compound (F):  
a compound containing a structure represented by the following formula (6) in a main chain and having at least one functional group represented by the following formula (7):
- Formula (6):
- $$\text{---}\left(\text{X}^4\text{---R}^{10}\right)_r\text{---} \quad (6)$$
- Formula (7):
- $$\text{CH}_2=\text{CR}^{11}\text{---CONH---} \quad (7)$$
- wherein  $X^4$  is  $-\text{O}-$ ,  $-\text{COO}-$  or  $-\text{OCOO}-$ ;  $R^{10}$  is a hydrocarbon group having 3 to 6 carbons;  $R^{11}$  is hydrogen atom or a methyl group; "r" is an integer from 1 to 50; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.
21. (Withdrawn) A resin composition according to Claim 20, wherein  $R^{10}$  of the structure represented by the formula (5) of the acrylamide compound (F) is at least one selected from the group consisting of  $-\text{C}_3\text{H}_6-$  and  $-\text{C}_4\text{H}_8-$ .

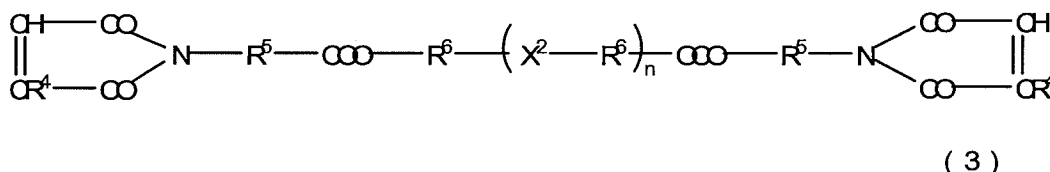
22. (Withdrawn) A resin composition according to Claim 20, wherein  $X^4$  of the structure represented by the formula (5) of the acrylamide compound (E) is  $-O-$ .

23. (Currently amended) A resin composition used as an adhesive for bonding a semiconductor chip or a heat dissipating member, comprising at least a silver powder (A) having an average particle size diameter of 1 to 30  $\mu\text{m}$ , the following compound (B), a thermal radical initiator (C) and the following allyl ester compound (G), and substantially not containing a photo polymerization initiator:

Compound (B):

a bis-maleimide compound (B') represented by the following formula (3):

Formula (3)



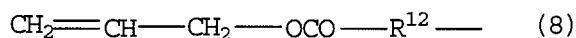
wherein  $X^2$  is  $-O-$ ; each  $R^4$  is a hydrogen atom or a methyl group; each  $R^5$  is a hydrocarbon group having 1 to 11 carbons and containing no aromatic group; each  $R^6$  is a hydrocarbon group having 3 to 6 carbons and containing no aromatic group; "n" is an integer from 1 to 50; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other;

Allyl ester compound (G):

a compound having at least one functional group represented by the following formula

(8):

Formula (8):

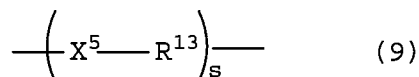


wherein  $R^{12}$  is a hydrocarbon group having 2 to 8 carbons.

24. (Original) A resin composition according to Claim 23, wherein  $R^{12}$  of the structure represented by the formula (8) of the allyl ester compound (G) does not contain an aromatic group.

25. (Previously presented) A resin composition according to Claim 23, wherein the allyl ester compound (G) contains a structure represented by the following formula (9):

Formula (9):



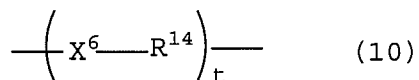
wherein  $X^5$  is  $-O-$ ,  $-COO-$  or  $-OCOO-$ ;  $R^{13}$  is a hydrocarbon group having 3 to 6 carbons; "s" is an integer from 1 to 50; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.

26. (Withdrawn) A resin composition according to Claim 1, further containing the following compound (H):

Compound (H):

a compound derived from a hydrocarbon having at least one C-C unsaturated bond in one molecule, which has a number average molecular weight of 500 to 5,000, contains a structure represented by the following formula (10) at its modified position, and has at least one functional group having a polymerizable C-C unsaturated bond:

Formula (10):



wherein  $X^6$  is  $-O-$ ,  $-COO-$  or  $-OCOO-$ ;  $R^{14}$  is a hydrocarbon group having 3 to 6 carbons; "t" is an integer from 1 to 50; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.

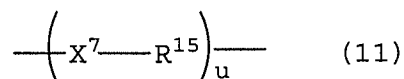
27. (Withdrawn) A resin composition according to Claim 26, wherein  $X^6$  is  $-O-$  and  $R^{14}$  is  $C_4H_8$  in the structure represented by the formula (10) of the compound (H).

28. (Withdrawn) A resin composition according to Claim 26, wherein a hydrocarbon led to the compound (H) and having at least one C-C unsaturated bond in one molecule is a butadiene polymer.

29. (Withdrawn) A resin composition according to Claim 26, wherein a hydrocarbon led to the compound (H) and having at least one C-C unsaturated bond in one molecule is an isoprene polymer.
30. (Withdrawn) A resin composition according to Claim 26, wherein the polymerizable C-C unsaturated bond of the compound (H) is a (meth)acryloyl group.
31. (Withdrawn) A resin composition according to Claim 1, further containing a reactive diluent (I).
32. (Withdrawn) A resin composition according to Claim 31, wherein the reactive diluent (I) is a vinyl compound which is in liquid form at room temperature other than the compounds (D) to (H).
33. (Withdrawn) A resin composition according to Claim 32, wherein the vinyl compound is a compound containing at least one (meth)acryloyl group.
34. (Withdrawn) A resin composition according to Claim 1, further containing a silane-based coupling agent (J).
35. (Withdrawn) A resin composition according to Claim 34, wherein the coupling agent (J) is a silane coupling agent having an S-S bond.
36. (Withdrawn) A resin composition according to Claim 34, wherein the coupling agent (J) further contains a silane coupling agent having a glycidyl group.
37. (Withdrawn) A resin composition according to Claim 1, containing a compound (K) having a glycidyl group other than the silane coupling agent having a glycidyl group.
38. (Withdrawn) A resin composition according to Claim 1, further containing the following compound (L) and the following compound (M):  
Compound (L):

a compound containing the following structure represented by the formula (11) in a main chain and having at least one glycidyl group:

Formula (11):



wherein  $\text{X}^7$  is  $-\text{O}-$ ,  $-\text{COO}-$  or  $-\text{OCOO}-$ ;  $\text{R}^{15}$  is a hydrocarbon group having 3 to 6 carbons; "u" is an integer from 2 to 50; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other;

Compound (M):

a compound having a functional group which can react with the glycidyl group of the compound (L).

39. (Withdrawn) A compound according to Claim 38, wherein the repeating unit ( $\text{X}^7\text{-R}^{15}$ ) of the compound (L) is the same as the repeating unit ( $\text{X}^1\text{-R}^1$ ) of the compound (M).

40. (Withdrawn) A semiconductor device containing the resin composition according to Claim 1 as a die attach material.

41. (Withdrawn) A semiconductor device containing the resin composition according to Claim 1 as a material for bonding a heat dissipating member.